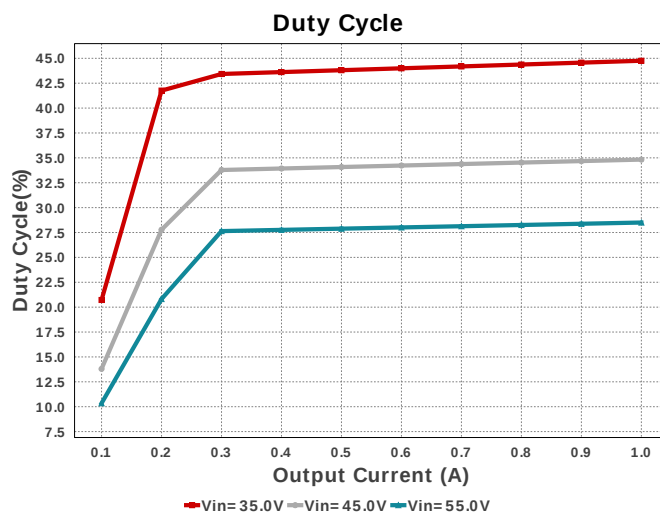
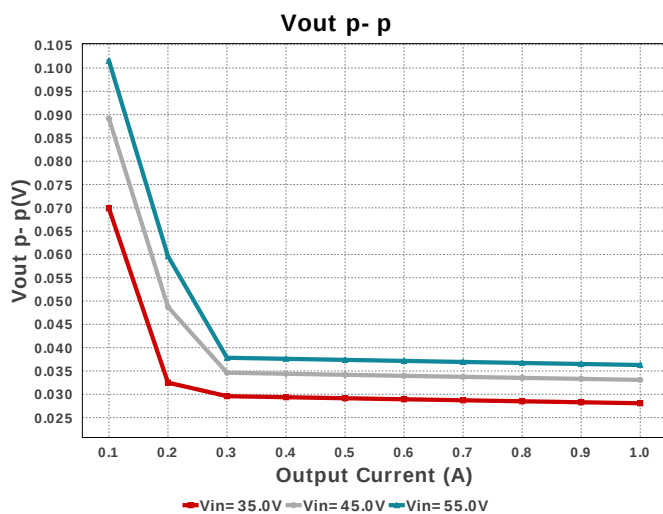
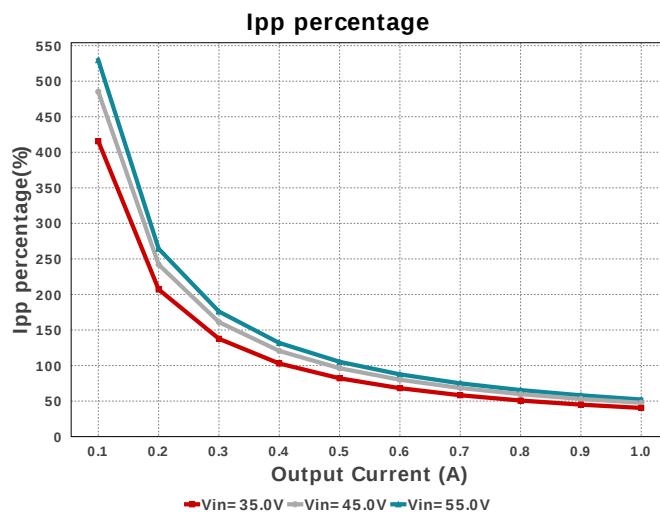
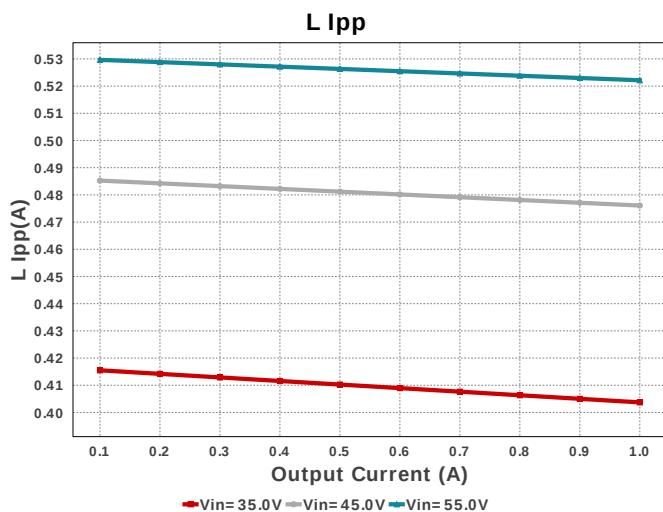
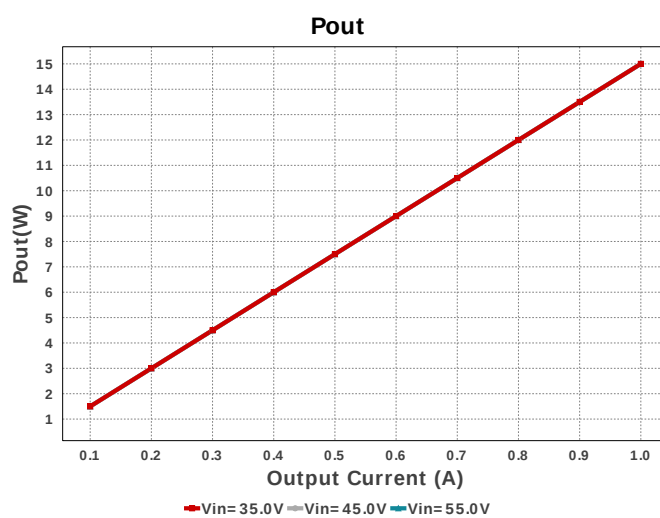
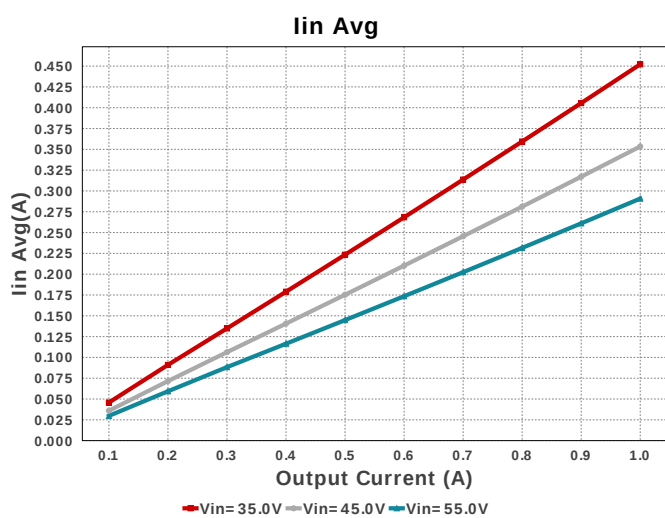
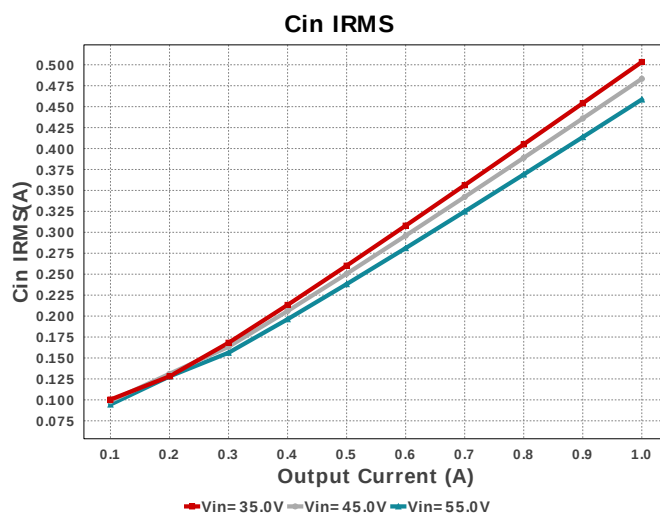
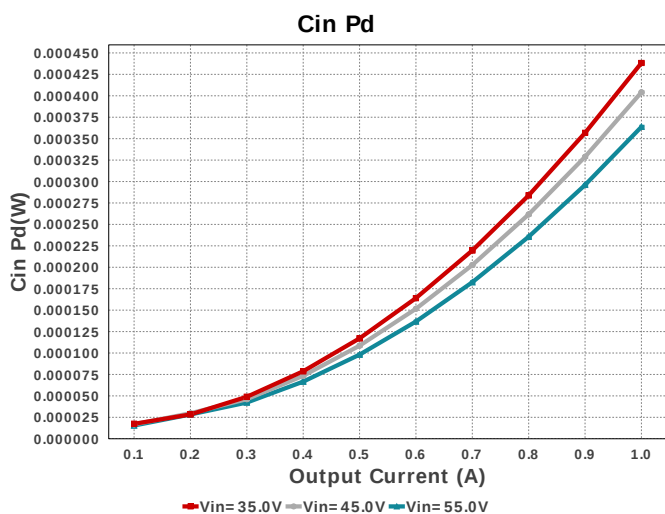
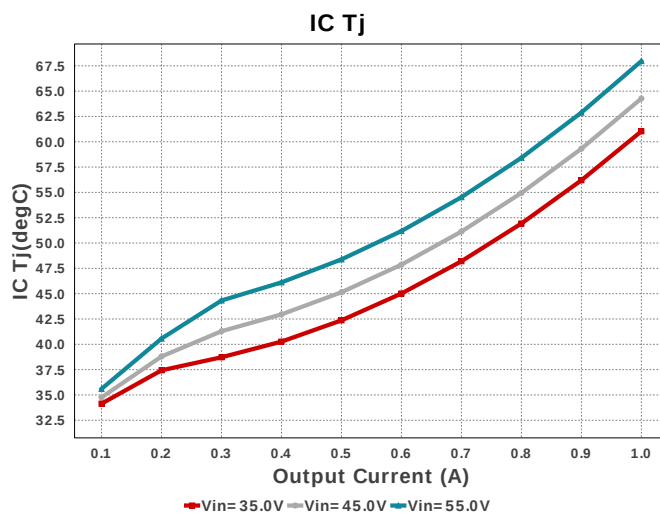
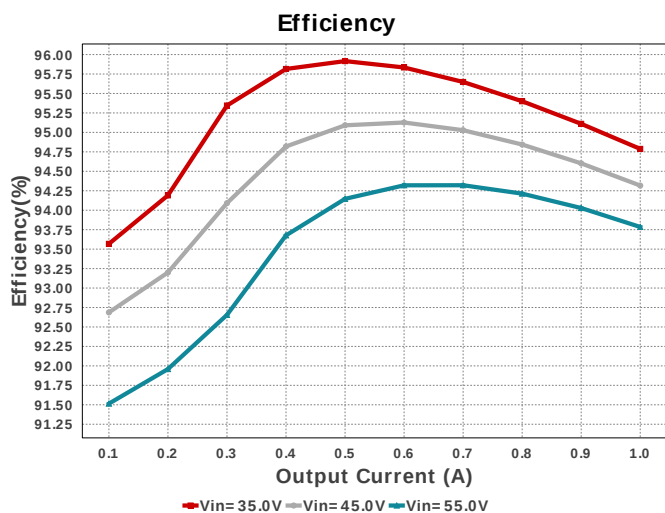


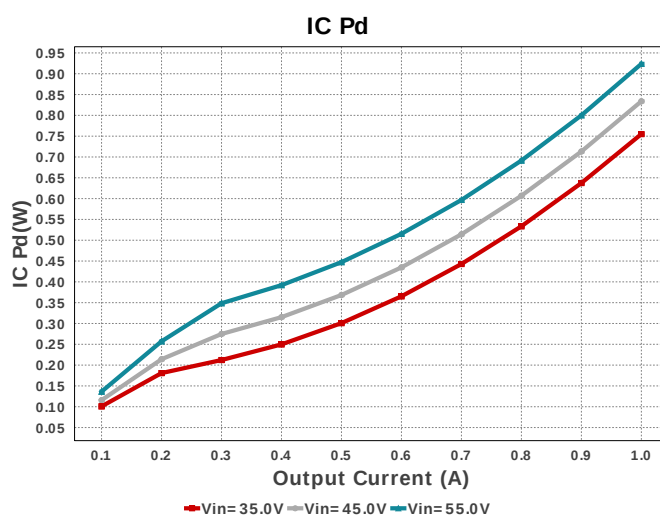
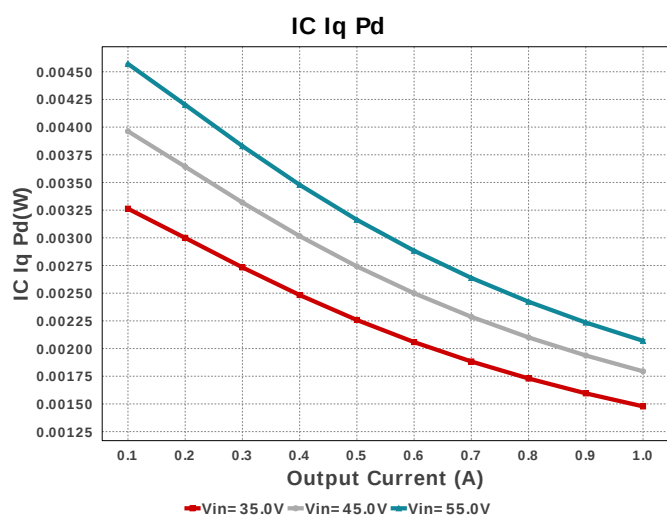
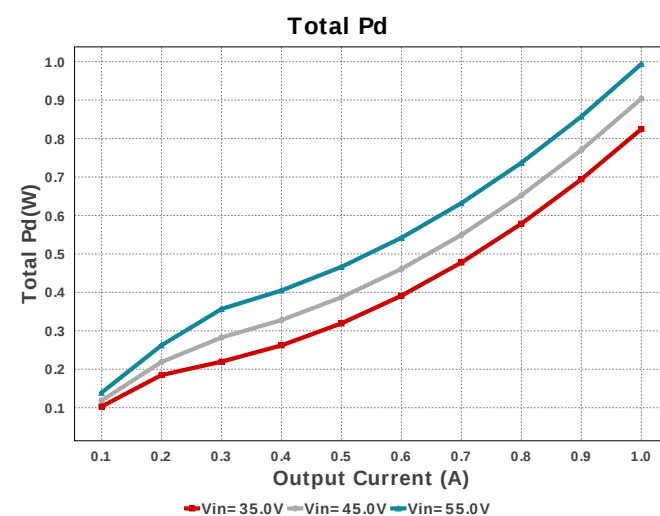
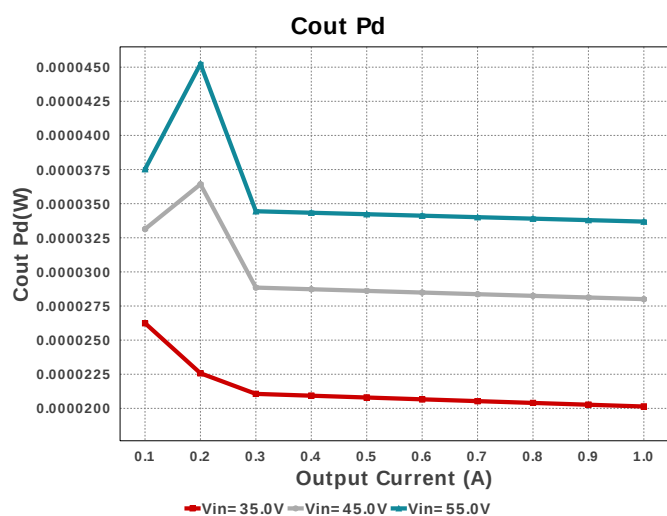
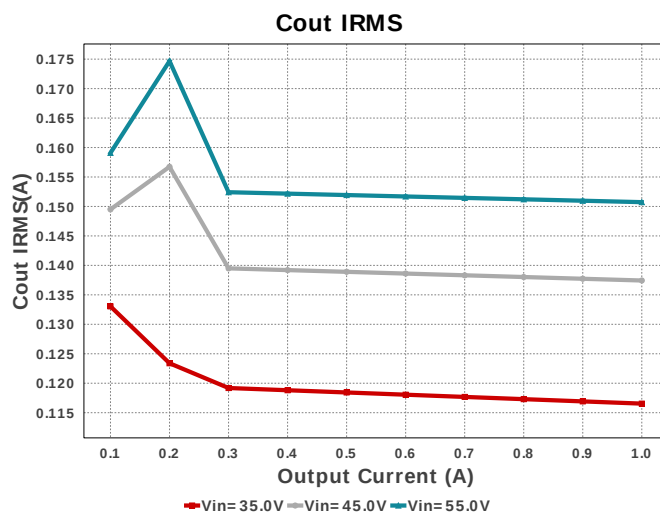
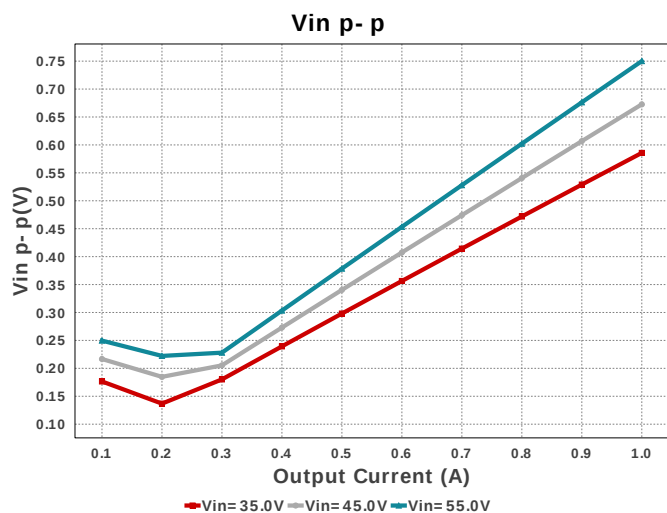


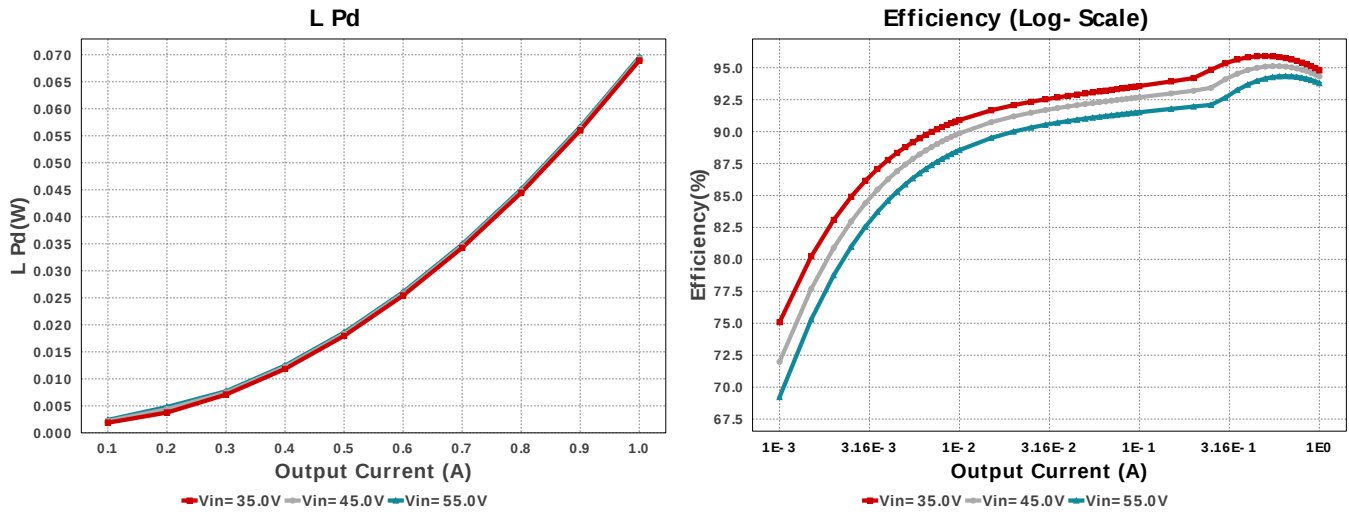
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Topology = Buck
Created = 2019-06-26 11:49:42.159
BOM Cost = \$3.21
BOM Count = 13
Total Pd = 0.99W

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbt	Yageo	RC0603FR-07576KL Series= ?	Res= 576.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
Ron	Vishay-Dale	CRCW0805124KFKEA Series= CRCW..e3	Res= 124.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	0805 7 mm ²
Rr	Yageo	RC0603FR-07634KL Series= ?	Res= 634.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
U1	Texas Instruments	LM5164QDDARQ1	Switcher	1	\$1.81	DDA0008E_N 55 mm ²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	458.652 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	363.93 μ W	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	151.946 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	34.231 μ W	Capacitor	Output capacitor power dissipation
5.	IC Iq Pd	2.07 mW	IC	IC Iq Pd
6.	IC Pd	921.47 mW	IC	IC power dissipation
7.	IC Tj	67.872 degC	IC	IC junction temperature
8.	ICThetaJA	41.1 degC/W	IC	IC junction-to-ambient thermal resistance
9.	Iin Avg	290.76 mA	IC	Average input current
10.	Ipp percentage	52.636 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
11.	L Ipp	526.36 mA	Inductor	Peak-to-peak inductor ripple current
12.	L Pd	69.57 mW	Inductor	Inductor power dissipation
13.	Cin Pd	363.93 μ W	Power	Input capacitor power dissipation
14.	Cout Pd	34.231 μ W	Power	Output capacitor power dissipation
15.	IC Pd	921.47 mW	Power	IC power dissipation
16.	L Pd	69.57 mW	Power	Inductor power dissipation
17.	Total Pd	991.811 mW	Power	Total Power Dissipation
18.	BOM Count	13	System	Total Design BOM count
19.	Duty Cycle	28.502 %	System	Duty cycle
20.	Efficiency	93.798 %	System	Steady state efficiency
21.	FootPrint	348.0 mm ²	System	Total Foot Print Area of BOM components
22.	Frequency	313.517 kHz	System	Switching frequency
23.	Iout	1.0 A	System	Iout operating point
24.	Mode	CCM	System	Conduction Mode
25.	Pout	15.0 W	System	Total output power
26.	Total BOM	\$3.21	System	Total BOM Cost
27.	Vin	55.0 V	System	Vin operating point
28.	Vin p-p	756.104 mV	System	Peak-to-peak input voltage
29.	Vout	15.0 V	System	Operational Output Voltage
30.	Vout Actual	15.052 V	System	Vout Actual calculated based on selected voltage divider resistors
31.	Vout Tolerance	2.878 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
32.	Vout p-p	36.87 mV	System	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	1.0	Maximum Output Current
VinMax	55.0	Maximum input voltage
VinMin	35.0	Minimum input voltage
Vout	15.0	Output Voltage
base_pn	LM5164-Q1	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

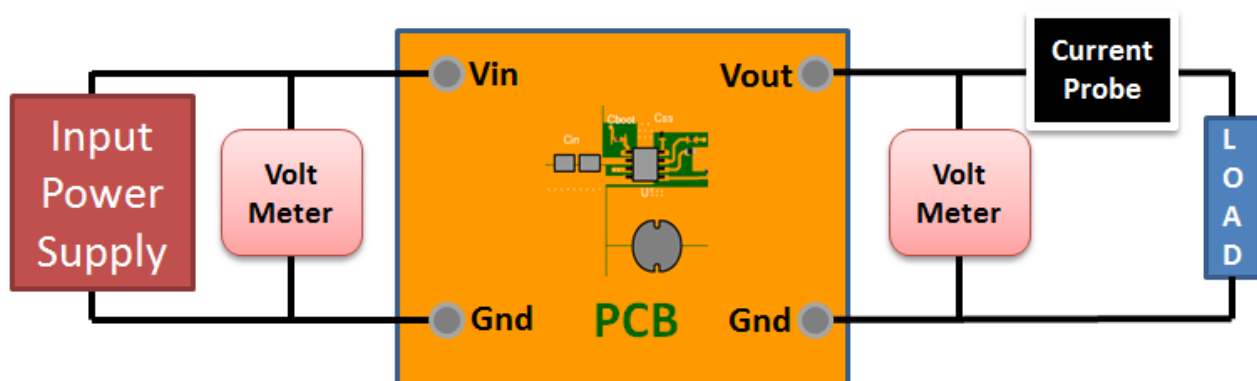
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 35.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. The LM5164-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application
2. Master key : 40EE3F1E021441DB[v1]
3. **LM5164-Q1** Product Folder : <http://www.ti.com/product/lm5164%2Dq1> : contains the data sheet and other resources.

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